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July 2008 Power-SPMTM

FP7G50US60

Transfer Molded Type IGBT Module

General Description

Fairchild's New IGBT Modules (Transfer Molded Type) provide low conduction and switching losses as well as short circuit ruggedness. They are designed for applications such as Motor control, Uninterrupted Power Supplies (UPS) and general Inverters where short circuit ruggedness is a required feature.

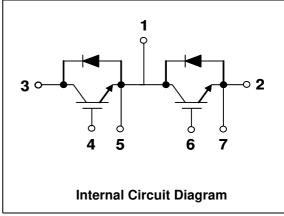
Features

- Short Circuit rated 10us @Tc=100°C, Vge=15V
- · High Speed Switching
- Low Saturation Voltage: Vce(sat) =2.2V @Ic=50A
- · High Input Impedance
- · Fast & Soft Anti-Parallel FWD

Application

- Welders
- · AC & DC Motor Controls
- · General Purpose Inverters
- Robotics
- · Servo Controls
- UPS





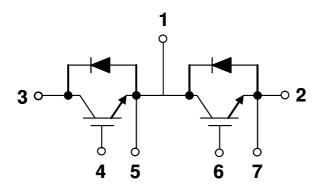
Absolute Maximum Ratings

| Symbol | Description | Rating | Units | |
|---------------------|---|--------------------------|-------------|----|
| V _{CES} | Collector-Emitter Voltage | | 600 | V |
| V _{GES} | Gate-Emitter Voltage | | ± 20 | V |
| I _C | Collector Current | @ T _C = 25°C | 50 | Α |
| I _{CM (1)} | Pulsed Collector Current | | 100 | Α |
| I _F | Diode Continuous Forward Current | @ T _C = 100°C | 50 | Α |
| I _{FM} | Diode Maximum Forward Current | 100 | Α | |
| T _{SC} | Short Circuit Withstand Time @ T _C = 100°C | | 10 | us |
| P_{D} | Maximum Power Dissipation @ T _C = 25°C | | 250 | W |
| T_J | Operating Junction Temperature | | -40 to +125 | °C |
| T _{stg} | Storage Temperature Range | | -40 to +125 | °C |
| V _{iso} | Isolation Voltage @ AC 1minute | | 2500 | V |
| Mounting | Power Terminals Screw : M5 | 2.0 | N.m | |
| Torque | Mounting Screw : M5 | 2.0 | N.m | |

Pin Configuration and Pin Description



Top View



Internal Circuit Diagram

Pin Description

| Pin Number | Pin Description | |
|------------|---|--|
| 1 | Emitter of Q1, IGBT, Collector of Q2, IGBT | |
| 2 | Emitter of Q2, IGBT | |
| 3 | Collector of Q1, IGBT | |
| 4 | Gate of Q1, IGBT | |
| 5 | Emitter of Q1, IGBT | |
| 6 | Gate of Q2, IGBT | |
| 7 | Emitter of Q2, IGBT | |

Electrical Characteristics ($T_J = 25$ °C, Unless Otherwise Specified)

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|---|---|--|-----|------|-------|-------|
| Off Char | racteristics | | | | | |
| BV _{CES} | Collector-Emitter Breakdown Voltage | $V_{GE} = 0V, I_C = 250\mu A$ | 600 | - | - | V |
| ΔBV _{CES} / ΔΤ _J | Temperature Coeff. of Breakdown Voltage | V _{GE} = 0V, I _C = 1mA | - | 0.6 | - | ٧ |
| I _{CES} | Collector Cut-off Current | V _{CE} = V _{CES} , V _{GE} = 0V | - | - | 250 | uA |
| I _{GES} | Gate-Emitter Leakage Current | $V_{GE} = V_{GES}, V_{CE} = 0V$ | - | - | ± 100 | nA |
| On Char | racteristics | | | | | |
| V _{GE(th)} | G-E Threshold Voltage | $V_{GE} = 0V$, $I_C = 50$ mA | 5.0 | 6.0 | 8.5 | V |
| V _{CE(sat)} | Collector to Emitter Saturation Voltage | I _C = 50A, V _{GE} = 15V | - | 2.2 | 2.8 | V |
| | c Characteristics | | | 1 | 1 | |
| C _{ies} | Input Capacitance | | | 2920 | | рF |
| C _{oes} | Output Capacitance | $V_{CE} = 30V, V_{GE} = 0V,$ $f = 1MHz$ | | 400 | | pF |
| C _{res} | Reverse Capacitance | | | 75 | | pF |
| | Rise Time | | _ | 40 | _ | ns |
| t _{d(on)} | Turn-On Delay Time | | - | 58 | - | ns |
| t _r | | | - | | | |
| t _{d(off)} | Turn-Off Delay Time | $V_{CC} = 300 \text{ V}, I_{C} = 50\text{A},$ | - | 107 | - | ns |
| t _f | Fall Time | $R_G = 5.9\Omega$, $V_{GE} = 15V$ Inductive Load, $T_C = 25^{\circ}C$ | - | 140 | - | ns |
| E _{on} | Turn-On Switching Loss | - | - | 0.75 | - | mJ |
| E _{off} | Turn-Off Switching Loss | | - | 0.54 | - | mJ |
| E _{ts} | Total Switching Loss | | - | 1.29 | - | mJ |
| t _{d(on)} | Turn-On Delay Time | | - | 53 | - | ns |
| t _r | Rise Time | | - | 40 | - | ns |
| t _{d(off)} | Turn-Off Delay Time | $V_{CC} = 300 \text{ V}, I_{C} = 50\text{A},$ | - | 106 | - | ns |
| t _f | Fall Time | $R_G = 5.9\Omega$, $V_{GE} = 15V$ Inductive Load, $T_C = 125^{\circ}C$ | - | 274 | - | ns |
| E _{on} | Turn-On Switching Loss | | - | 1.09 | - | mJ |
| E _{off} | Turn-Off Switching Loss | | - | 1.68 | - | mJ |
| E _{ts} | Total Switching Loss | V 200 V V | - | 2.77 | - | mJ |
| T _{sc} | Short Circuit Withstand Time | V _{CC} = 300 V, V _{GE} = 15V @ T _C = 100°C | 10 | - | - | us |
| Qg | Total Gate Charge | | - | 136 | - | nC |
| | | | | | | |
| Q _{ge} | Gate-Emitter Charge | $V_{CE} = 300 \text{ V}, I_{C} = 50 \text{A}, V_{GE} = 15 \text{V}$ | - | 26 | - | nC |

$\textbf{Electrical Characteristics of DIODE} \ \, (\textbf{T}_{J} = 25^{\circ}\textbf{C}, \ \, \textbf{Unless Otherwise Specified})$

| Symbol | Parameter | Con | ditions | Min | Тур | Max | Units |
|-----------------|---|--|------------------------|-----|-----|-----|-------|
| V_{FM} | Diode Forward Voltage | I _F = 50A | T _C = 25°C | - | 1.9 | 2.8 | V |
| | | | T _C = 100°C | - | 1.8 | - | |
| t _{rr} | Diode Reverse Recovery Time | I _F = 50A di / dt = 100 A/us | T _C = 25°C | - | 76 | 100 | ns |
| | | | T _C = 100°C | - | 138 | | |
| | I _{rr} Diode Peak Reverse Recovery Current | | T _C = 25°C | - | 4 | 5.2 | A |
| I _{rr} | | | T _C = 100°C | - | 6 | | |
| Q _{rr} | Diode Reverse Recovery Charge | | T _C = 25°C | - | 152 | 260 | nC |
| | | | T _C = 100°C | - | 404 | | |

Thermal Characteristics

| Symbol | Parameter | Тур. | Max. | Units |
|-----------------|---|------|------|-------|
| $R_{\theta JC}$ | Junction-to-Case (IGBT Part, per 1/2 Module) | - | 0.4 | °C/W |
| $R_{\theta JC}$ | Junction-to-Case (DIODE Part, per 1/2 Module) | - | 1.0 | °C/W |
| $R_{\theta CS}$ | Case-to-Sink (Conductive grease applied) | 0.05 | - | °C/W |
| Weight | Weight of Module | - | 90 | g |

Typical Performance Characteristics

Fig 1. Typical Output Characteristics

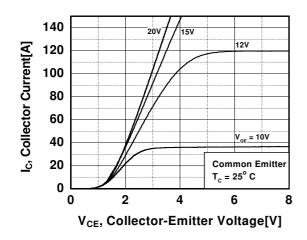


Fig 2. Typical Saturation Voltage Characteristics

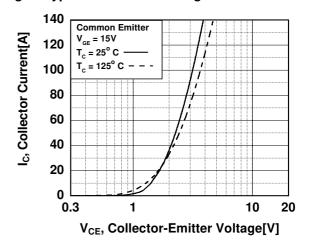


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

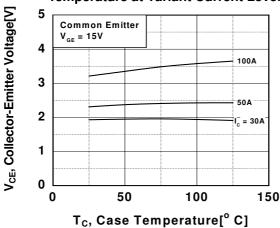


Fig 4. Load Current vs. Frequency

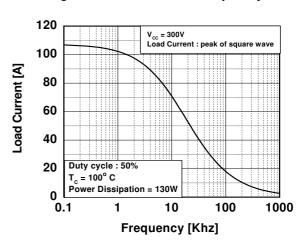


Fig 5. Saturation Voltage vs. V_{GF}

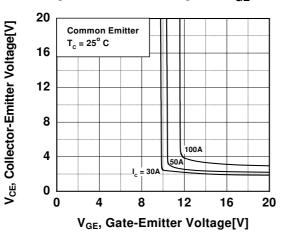
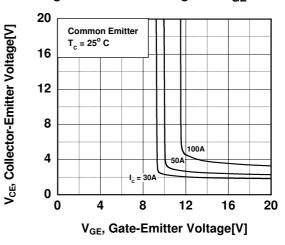


Fig 6. Saturation Voltage vs. V_{GF}



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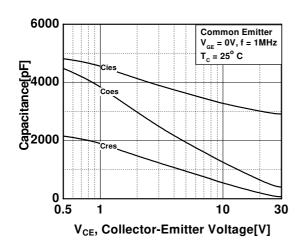


Fig 8. Turn-On Characteristics vs.
Gate Resistance

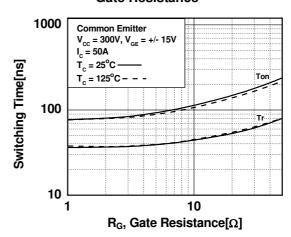


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

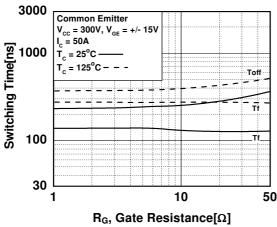


Fig 10. Switching Loss vs. Gate Resistance

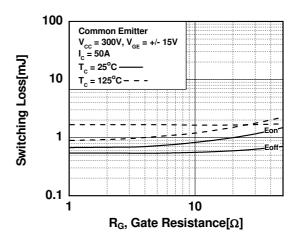


Fig 11. Turn-On Characteristics vs. Collector Current

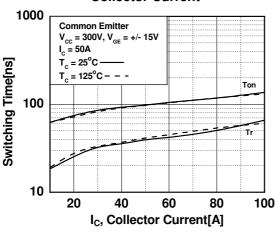
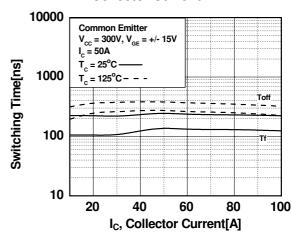


Fig 12. Turn-Off Characteristics vs. Collector Current





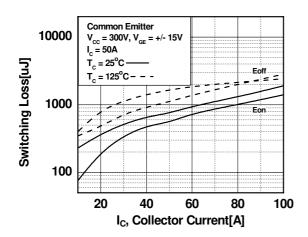


Fig 14. Gate Charge Characteristics

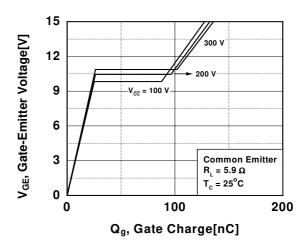


Fig 15. SOA Characteristics

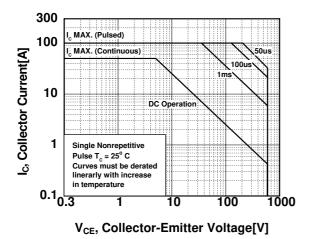


Fig 16. Turn-Off SOA Characteristics

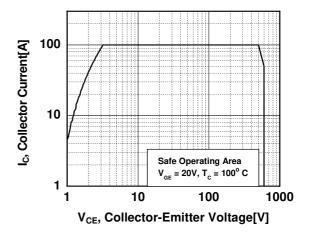


Fig 17. RBSOA Characteristics

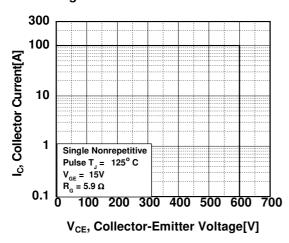


Fig 18. Transient Thermal Impedance

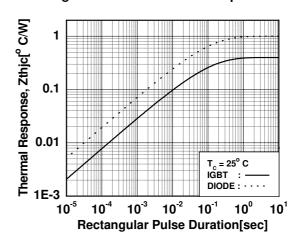


Fig 19. Forward Characteristics

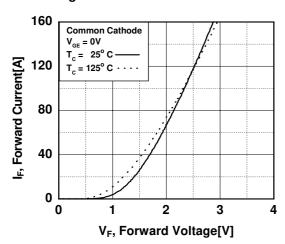
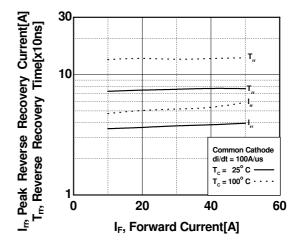
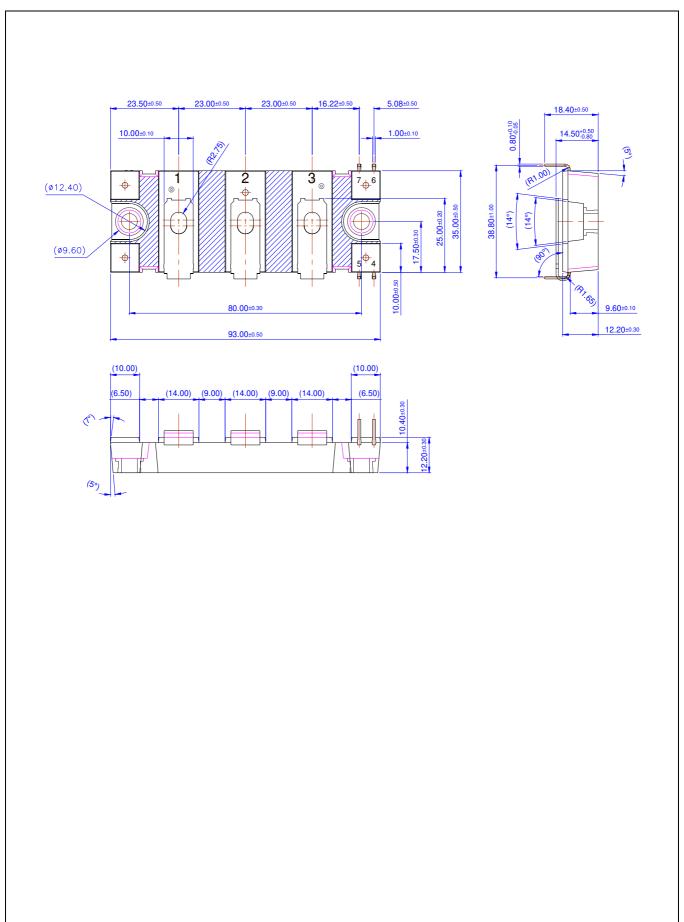


Fig 20. Reverse Recovery Characteristics









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